



Material Content Data Sheet



Sales Product Name		BTS740S2		Issued		24. January 2018		
MA#		MA001208544						
Package		PG-DSO-20-31		Weight*		500.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.627	2.52	2.52	25215	25215
leadframe	inorganic material	phosphorus	7723-14-0	0.042	0.01		85	
	non noble metal	zinc	7440-66-6	0.169	0.03		338	
	non noble metal	iron	7439-89-6	3.388	0.68		6766	
wire	non noble metal	copper	7440-50-8	137.580	27.47	28.19	274741	281930
	noble metal	gold	7440-57-5	2.989	0.60	0.60	5969	5969
	encapsulation	organic material	carbon black	1333-86-4	0.670	0.13		1338
encapsulation	plastics	epoxy resin	-	30.820	6.15		61546	
	inorganic material	silicondioxide	60676-86-0	303.511	60.61	66.89	606098	668982
leadfinish	non noble metal	tin	7440-31-5	2.746	0.55	0.55	5483	5483
plating	noble metal	silver	7440-22-4	3.187	0.64	0.64	6364	6364
glue	plastics	epoxy resin	-	0.531	0.11		1060	
	noble metal	silver	7440-22-4	2.502	0.50	0.61	4997	6057
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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